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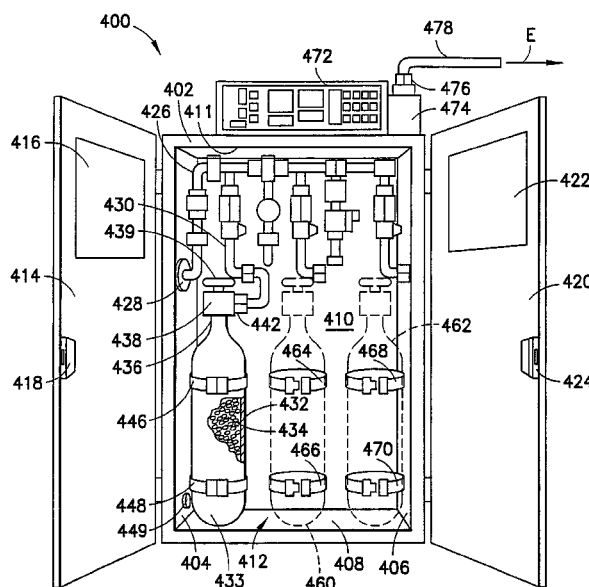
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- (74) Agent: **ZITZMANN, Oliver, A., M.**; Advanced Technology Materials, Inc., 7 Commerce Drive, Danbury, CT 06810 (US).
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- (71) Applicant (for all designated States except US): **ADVANCED TECHNOLOGY MATERIALS, INC.** [US/US]; 7 Commerce Drive, Danbury, CT 08610 (US).
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(54) Title: GAS CABINET ASSEMBLY COMPRISING SORBENT-BASED GAS STORAGE AND DELIVERY SYSTEM



(57) Abstract: A gas supply system including a gas cabinet (402) defining an enclosure including therein a gas dispensing manifold (426) and one or more adsorbent-based gas storage and dispensing vessels (433),(460),(462) mounted in the enclosure and joined in gas flow communication with the gas dispensing manifold (426). The enclosure may be maintained under low or negative pressure conditions for enhanced safety in the event of leakage of gas from the gas storage and dispensing vessels (433),(460),(462) in the enclosure. The gas supply system may be coupled to a gas-consuming unit in a semiconductor manufacturing facility, e.g., an ion implanter, an etch chamber, or a chemical vapor deposition reactor.